# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

## Marketing Name / Model
[List multiple models if applicable.]

HP ProOne 400 G1 AIO Business PC (19.5" Non-Touch)

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB, Webcam, converter board, power button board</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>7</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>2# X10</td>
</tr>
<tr>
<td>Description #2</td>
<td>1# X10</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Please refer to the 3.2.3 disassemble rear cover
2. Please refer to the 3.2.4 disassemble the stand
3. Please refer to the 3.2.5 disassemble MB Shielding
4. Please refer to the 3.2.6 disassemble HDD & ODD
5. Please refer to the 3.2.7 disassemble Speaker
6. Please refer to the 3.2.8 disassemble CPU thermal module
7. Please refer to the 3.2.9 disassemble FAN Module
8. Please refer to the 3.2.10 disassemble converter board
9. Please refer to the 3.2.11 disassemble Webcam
10. Please refer to the 3.2.12 disassemble Wireless card
11. Please refer to the 3.2.13 disassemble the cables connected to MB and Base pan
12. Please refer to the 3.2.14 disassemble MB and MB battery
13. Please refer to the 3.2.15 disassemble CPU and DDR
14. Please refer to the 3.2.16 separate Base pan and front bezel and panel
15. Please refer to the 3.2.17 remove Mouse/Keyboard Battery/MB
16. Please refer to the 3.2.18 remove power supply
17.
18.
19.
20.
21.
22.
23.
24.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Place the system

2. Disassemble rear cover
   Remove 2pcs screws with circle in red.

3. Disassemble stand
   Remove 4pcs screws on both left and right so you can remove stand.
4. Disassemble VESA support bracket
   Remove 3pcs screws with circles in red

5. Disassemble MB shielding
   (1) Remove 3pcs screws with circles in red
6. Disassemble HDD & ODD
Remove 1pcs screw with circles in red from HDD and pull backward to disengage the HDD from base pan.
Remove 1pcs screw and push ODD forward to slide from ODD cage.

7. Disassemble speaker
Remove 4pcs screws from left and right,
Also remove the speaker cable with in yellow circle in order to take out two speakers from system.
8. Disassemble CPU thermal module
Remove 5pcs screws and remove away the thermal module.

9. Disassemble FAN Module
Remove 3pcs screws and remove the cable with in yellow circle to disassemble the fan.
10, Disassemble converter board
Remove two cables and 2pcs screws to remove the converter board.

11, Disassemble Webcam
Remove the cable and screw in order to disengage the webcam module and mechanical parts.
12, Disassemble Wireless card
Remove one or two cables and 1pcs screw in order to remove wireless card.

13, Disassemble the cables connected to MB and Base pan.
(1), Remove the HDD/ODD cable
Remove the cable with circles in yellow and remove 4pcs screws with circles in red.
(2) Remove LVDS cable and converter cable connected to MB and take away converter cable.

(3) Remove antenna cable on the Base pan and take away the cable.
14. Disassemble MB and MB battery
Remove 9pcs screws to disassemble the INTEL(Cotton) MB

Pull backward the clip with in yellow circle to release the battery
15, Disassemble CPU and DDR
(1) Remove the CPU by releasing the hook for Intel

(2) Pull both clicks outward that holding the memory to remove the DDR.

16, Separate Base pan and front bezel and panel
(1) Remove 14pcs screws with circles in red to separate base pan and front bezel.
(2), Remove 4pcs screws with circles in red to separate base pan and AUO/LG Panel

17, Remove Mouse/Keyboard Battery/MB

PSG instructions for this template are available at EL-MF877-01
18. Remove power supply

Cutting here & separated

Cutting here & separated

Cutting here & separated

Cutting here & separated

Remove PCBA

Cutting here & separated

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